

2822



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

8/A Amdd  
6.5.03  
A. Wee

In re the Application of:

Liang, et al.

Docket No.: TI-32508

Serial No.: 10/032,907

Examiner: Rose, Kiesha L.

Filed: 12/28/01

Art Unit: 2822

For: Method and Apparatus for Flip Chip Device Assembly by Radiant Heating

Amendment under 37 CFR 1.111

Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

5-27-03

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 02/26/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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TECHNOLOGY CENTER 2800